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Part Number: [73943-6000](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 72 Circuits

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

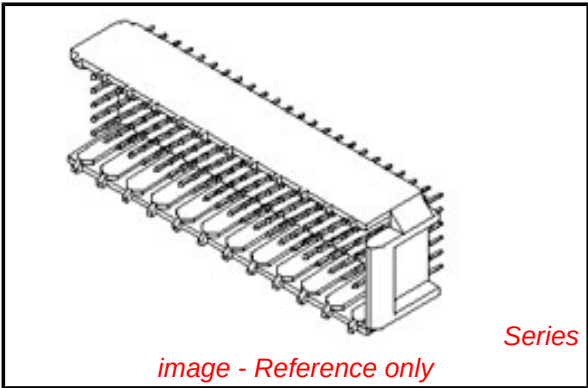
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73943](#)
Application Backplane
Comments Solder Tail
Component Type PCB Header
Overview [HDM® Backplane Connector System](#)
Product Name HDM®
Style N/A
UPC 800754887380

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 3.554/g
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.50mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 2.50mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole



EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Low-Halogen Status
Low-Halogen



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73943Series](#)

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Sales Drawing	SD-73943-001
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